Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1159	adhesive same((youngs elastic) adj modulus) and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 09:07
L2	7	L1 and ((ball adj grid adj array) BGA)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 09:14
L3	6	L1 and ((thermoplastic adj resin) same ((glass adj transition) ("T.sub. g")))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 09:25
L4	1084	257/783.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 09:26
L5	202	257/783.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 09:26
L6	33	L5 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:04
L7	86	438/118.ccls. and (elastic youngs) adj modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:09
L8	13	L7 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:09

L9	1517	438/118.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:09
L10	400	438/118.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:09
L11	27	L10 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:14
L12	82	438/125,123.ccor. and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:13
L13	0	438/125,123.ccor. and @ad<"19960530" and (elastic youngs) adj module	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:13
L14	0	438/125,123.ccor. and @ad<"19960530" and (elastic youngs) adj modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:14
L15	6290	428/343,345,901,306.6.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:27
L16	3281	L15 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:27

L17	80	L16 and (elastic youngs) adj modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:15
L18	10	L17 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:15
L19	801	428/343,345,901,306.6.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:27
L20	183	L19 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:29
L21	657	156/325.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:30
L22	183	L20 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:30
L23	9	L22 and (youngs elastic) adj modulus	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:30
L24	0	L22 and (youngs elastic) adj modulus and (semiconductor (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:30

L25	61	156/325.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:30
L26	17	L25 and @ad<"19960530"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/01/13 10:30